

Title (en)
METHOD AND DEVICE FOR CONNECTING CHIPS

Title (de)
VERFAHREN UND EINRICHTUNG ZUM VERBINDEN VON CHIPS

Title (fr)
PROCEDE ET DISPOSITIF DE CONNEXION DE PUCES

Publication
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Application
EP 04805792 A 20041028

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• FR 0350774 A 20031103

Abstract (en)
[origin: WO2005045934A2] The invention relates to an electronic device comprising: a circuit (20, 50) having a first and second face, said first face being fitted with electrical connecting means (22, 53); a transfer element (24, 50) comprising a first and second face, assembled with its first face placed against the second face of the active element, and comprising electrical connecting means (26, 62) on its second face, and; a connection (32, 56) between the electrical connecting means of the active element and those of the transfer element.

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IPC 8 full level
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C-Set (source: EP US)
1. **H01L 2224/48091 + H01L 2924/00014**
2. **H01L 2924/10253 + H01L 2924/00**
3. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00**
4. **H01L 2924/12041 + H01L 2924/00**
5. **H01L 2924/00014 + H01L 2224/45099**
6. **H01L 2924/00014 + H01L 2224/45015 + H01L 2924/207**

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